



EFW

Docket No.: 060188-0594

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of	:	Customer Number: 20277
	:	
Shuji HIRAO	:	Confirmation Number: 6629
	:	
Application No.: 10/624,564	:	Group Art Unit: 1753
	:	
Filed: July 23, 2003	:	Examiner: WONG, Edna
	:	
For: METHOD AND APPARATUS FOR PLATING SUBSTRATE		

**RESPONSE TO RESTRICTION REQUIREMENT**

Mail Stop Restriction Requirement  
Honorable Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Noting the Office Action of March 24, 2006 wherein restriction has been required, Applicant hereby elects Group I (claims 1-11) for prosecution in the above-identified application.

To the extent necessary, a petition for an extension of time under 37 C.F.R. 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

McDERMOTT WILL & EMERY LLP

Michael E. Fogarty  
Registration No. 36,139  
**Please recognize our Customer No. 20277  
as our correspondence address.**

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**Date: April 24, 2006**